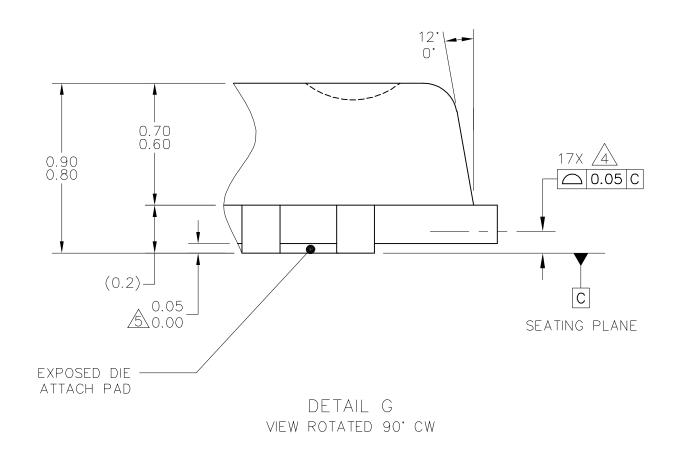


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		STANDARD: NON-JEDEC		
3 X 3 X 0.85, 0.5 PITCH,	16 IERMINAL	S0T758-	- 4 1	2 JAN 2016





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NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- THIS DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM TERMINAL TIP.
- A BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
- 1 THIS DIMENSION APPLIES ONLY FOR TERMINALS.

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